SEP 2 9 2003 Docket No.: M&N-IT-471

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By:

Date: September 26, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applic. No.

10/632,759

Inventor

Hans-Dieter Weigel

Filed

August 1, 2003

TC/A.U.

to be assigned

Examiner

to be assigned

Docket No.

M&N-IT-471

Customer No.:

24131

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. 1.98

Hon. Commissioner for Patents; Alexandria, VA 22313-1450

Sir:

In accordance with 37 C.F.R. 1.98, copies of the following patents and/or publications are submitted herewith:

U.S. Patent No. 5,302,778 (Maurinus), dated April 12, 1994;

U.S. Patent No. 5,475,783 (Kurashima), dated December 12, 1995;

U.S. Patent No. 5,781,682 (Cohen et al.), dated July 14, 1998;

Applic. No. 10/632,759 IDS filed September 26, 2003

German Translation No. DE 694 29 700 T2 (Kurashima), dated April 5, 1995, corresponding to U.S. Patent No. 5,475,783;

German Translation No. DE 693 22 821 T2 (Maurinus et al.), dated March 2, 1994, corresponding to U.S. Patent No. 5,302,778;

International Publication No. WO 02/44796 A2 (Mertz), dated June 6, 2002;

International Publication No. WO 02/093696 A2 (Pommer et al.), dated November 21, 2002;

"Metallized Particle Interconnect – A Simple Solution for High-Speed, High-Bandwidth Applications", Tyco/Electronics, pp. 1-7;

German Office action dated August 25, 2003.

Respectfully submitted,

Mark P. Weichselbaum Reg. No. 43,248

For Applicants

Date: September 26, 2003

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